

16138 U.S. PTO

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

31281 U.S. PTO
10/721920



In re Patent Application of: Kie Y. Ahn et al.

Title: MULTILEVEL COPPER INTERCONNECT WITH DOUBLE PASSIVATION

Attorney Docket No.: 303.685US2

Customer No.: 21186

PATENT APPLICATION TRANSMITTAL

MAIL STOP PATENT APPLICATION

Commissioner for Patents

P.O. Box 1450

Alexandria, VA 22313-1450

We are transmitting herewith the following attached items and information (as indicated with an "X"):

- ☒ Return postcard.
- ☒ **DIVISIONAL** of prior Patent Application No. (09/584157) (under 37 CFR 1.53(b)) comprising:
 - ☒ Specification (39 pgs, including claims numbered 1 through 72 and a 1 page Abstract).
 - ☒ Formal Drawings (4 sheets).
 - ☒ Copy of signed Declaration (5 pgs) from prior application.
 - ☒ Copy of Power of Attorney from prior application (1 pg.).
 - ☒ Incorporation by Reference: *The entire disclosure of the prior application, from which a copy of the oath or declaration is supplied herewith, is considered as being part of the disclosure of the accompanying application and is hereby incorporated by reference therein.*
- ☒ Authorization to charge Deposit Account No. 19-0743 in the of \$3,253.00 to pay the filing fee.
- ☒ Prior application is assigned of record to Micron Technology, Inc.
- ☒ Information Disclosure Statement (2 pgs), Form 1449 (9pgs.) and copies of 22 citations.
- ☒ A Communication Concerning Related Applications (2 pgs.).

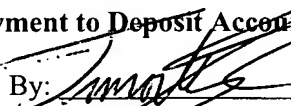
The filing fee has been calculated below as follows:

| | No. Filed | No. Extra | Rate | Fee |
|---|-----------|-----------|-----------|-----------|
| TOTAL CLAIMS | 72-20 | 52 | x 18.00 = | \$936.00 |
| INDEPENDENT CLAIMS | 21-3 | 18 | x 86.00 = | \$1548.00 |
| [] MULTIPLE DEPENDENT CLAIMS PRESENTED | | | | \$0.00 |
| BASIC FEE | | | | \$770.00 |
| TOTAL | | | | \$3253.00 |

Please consider this a PETITION FOR EXTENSION OF TIME for sufficient number of months to enter these papers. Please charge any additional required fees or credit overpayment to Deposit Account No. 19-0743.

SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A.

Customer Number: 21186

By: 
Atty: Timothy B. Clse
Reg. No. 40,957

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Date of Deposit: November 24, 2003

This paper or fee is being deposited on the date indicated above with the United States Postal Service pursuant to 37 CFR 1.10, and is addressed to The Commissioner for Patents, Mail Stop Patent Application, P.O. Box 1450, Alexandria, VA 22313-1450.

S/N Unknown

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

| | | | |
|-------------|--|-----------------|------------|
| Applicant: | Kie Y. Ahn et al. | Examiner: | Unknown |
| Serial No.: | Unknown | Group Art Unit: | Unknown |
| Filed: | Herewith | Docket: | 303.685US2 |
| Title: | MULTILEVEL COPPER INTERCONNECT WITH DOUBLE PASSIVATION | | |

COMMUNICATION CONCERNING RELATED APPLICATIONS

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Applicants would like to bring to the Examiner's attention the following related applications in the above-identified patent application:

| <u>Serial/Patent No.</u> | <u>Filing Date</u> | <u>Attorney Docket</u> | <u>Title</u> |
|--------------------------|---------------------|------------------------|---|
| 08/954,450 5,891,797 | October 20, 1997 | 303.348US1 | METHOD OF FORMING A SUPPORT STRUCTURE FOR AIR BRIDGE WIRING OF AN INTEGRATED CIRCUIT |
| 09/140,377 5,994,777 | August 26, 1998 | 303.348US2 | METHOD AND SUPPORT STRUCTURE FOR AIR BRIDGE WIRING OF AN INTEGRATED CIRCUIT |
| 09/119,355 6,509,590 | July 20, 1998 | 303.482US1 | ALUMINUM-BERYLLIUM ALLOYS FOR AIR BRIDGES |
| 09/854,540 | May 14, 2001 | 1303.013US1 | COPPER DUAL DAMASCENE INTERCONNECT TECHNOLOGY |
| 09/484,303 | January 18, 2000 | 303.648US1 | METHODS FOR MAKING INTEGRATED-CIRCUIT WIRING FROM COPPER, SILVER, GOLD, AND OTHER METALS |
| 10/349,015 | January 21, 2003 | 303.482US2 | ALUMINUM-BERYLLIUM ALLOYS FOR AIR BRIDGES |

COMMUNICATION CONCERNING RELATED APPLICATIONS

Serial Number: Unknown

Filing Date: Herewith

Title: MULTILEVEL COPPER INTERCONNECT WITH DOUBLE PASSIVATION

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Dkt: 303.685US2

Respectfully submitted,

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Date of Deposit: November 24, 2003

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